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**1 Influence of plasma treatment and cleaning on vacuum wafer bonding**
*Wei Bo Yu; Cher Ming Tan; Jun Wei; Shu Sheng Deng; Mui Ling Nai;*

Electronics Packaging Technology, 2003 5th Conference (EPTC 2003) , 10-12 Dec. 2003

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[\[Abstract\]](#)    [\[PDF Full-Text \(307 KB\)\]](#)    **IEEE CNF**
**2 Plasma-assisted InP-to-Si low temperature wafer bonding**
*Pasquariello, D.; Hjort, K.;*

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[\[Abstract\]](#)    [\[PDF Full-Text \(443 KB\)\]](#)    **IEEE JNL**
**3 Wafer to wafer direct bonding using surfaces activated by hydrogen plasma treatment**
*Choi, W.B.; Ju, C.M.; Ju, B.K.; Sung, M.Y.;*

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**4 Material properties of plasma-thinned bonded SOI wafers**
*Feng, T.; Matloubian, M.; Mathur, D.P.; Mumola, P.B.; Gardopee, G.J.;*

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[\[Abstract\]](#)    [\[PDF Full-Text \(136 KB\)\]](#)    **IEEE CNF**
**5 Surface quality of plasma-thinned bonded SOI wafers**
*Feng, T.; Matloubian, M.; Gardopee, G.J.; Mathur, D.P.;*

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#### 10 Low temperature direct bonding of nonhydrophilic surfaces

*Watt, V.H.C.; Bower, R.W.;*

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*Bollinger, L.D.; Gardopee, G.J.; Mathur, D.P.; Mumola, P.B.; Nester, J.F.;*

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*Hagen, R.; Ramm, J.; Zeiler, T.; Goller, B.;*

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**14 Utility of using power spectral density to characterize SOI layer thickness uniformity**

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**15 Thin-film transistors on plastic and glass substrates using silicon deposited by microwave plasma ECR-CVD**

*Lihong Teng; Anderson, W.A.;*

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